RELIABILITY REPORT

FOR

MAX4910ETE+
(MAX4911, MAX4912)

PLASTIC ENCAPSULATED DEVICES

March 16, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX4910ETE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX4910/MAX4911/MAX4912 quad, singlepole/double-throw (SPDT), clickless audio switches feature negative signal capability that allows signals as low as VCC - 5.5V to pass through without distortion. These analog switches have a low on-resistance, low supply current, and operate from a single +1.8V to +5.5V supply. The MAX4910/MAX4911/MAX4912 have internal shunt resistors that automatically discharge the capacitance at the normally open (NO) and normally closed (NC) terminals when they are not connected. The MAX4910/MAX4911 have shunt resistors on all NO and NC terminals and the MAX4912 has shunt resistors on all NO, NC1, and NC3 terminals. These shunt resistors reduce click-and-pop sounds that occur when switching audio signals between precharged points. A break-before-make feature further reduces popping. The MAX4910/MAX4912 control the switches in pairs with two control bits CB1 and CB2. The MAX4911 has one control bit to switch all four switches and an enable pin active-low EN to put the switches in a high-impedance mode. The MAX4912 has two terminals without shunt resistors for switching applications that do not require pre-discharge switching. The MAX4910/MAX4911/MAX4912 are available in a tiny 16-pin TQFN-EP (3mm x 3mm) package and operate over the -40°C to +85°C extended temperature range.

II. Manufacturing Information

A. Description/Function:	Quad-SPDT Clickless Audio Switches with Negative Signal Handling
B. Process:	S4
C. Number of Device Transistors:	
D. Fabrication Location:	California
E. Assembly Location:	ISPL Philippines, ASAT China, UTL Thailand, Unisem Malaysia
F. Date of Initial Production:	April 22, 2006

III. Packaging Information

A. Package Type:	16-pin TQFN 3x3
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2047
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	64°C/W
K. Single Layer Theta Jc:	6.9°C/W
L. Multi Layer Theta Ja:	48°C/W
M. Multi Layer Theta Jc:	6.9°C/W

IV. Die Information

A. Dimensions:	61 X 61 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.4 \times 10^{-9}$

λ = 22.4 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the S4 Process results in a FIT Rate of 0.28 @ 25C and 4.85 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AS73 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000 V per JEDEC JESD22-A114-D. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1

Reliability Evaluation Test Results

MAX4910ETE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data